

Type number	Package	Package description	Total product weight
74LVC1G86GX	SOT1226-3	X2SON5	0.61376 mg

12NC	Version	Pb-free soldering			Pb soldering			Number of processing cycles	Assembly site	RHF-indicator
		MSL	PPT	MPPT	MSL	PPT	MPPT			
935298385125	5	1	260	30 s	1	240	20 s	3	Nijmegen, Netherlands; Bangkok, Thailand; Seremban, Malaysia	

Subpart	Material group	Substances	CAS number	Mass(mg)	Mass(%) of subpart	Mass(%) of total product
Die	Doped silicon	Silicon (Si)	7440-21-3	0.03045	100.00000	4.96054
		subTotal		0.03045	100.00000	4.96054
Component	Additive	Non hazardous	Proprietary	0.00020	5.00000	0.03259
	Filler	Bisphenol-A/Epichlorohydrin Epoxy resin (generic)	25068-38-6	0.00020	5.00000	0.03259
		Silica -amorphous-	7631-86-9	0.00200	50.00000	0.32586
		Epoxy resin system	Proprietary	0.00120	30.00000	0.19552
	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	0.00040	10.00000	0.06517
		subTotal			0.00400	100.00000
Lead Frame	Copper alloy	Copper (Cu)	7440-50-8	0.23911	94.51000	38.95827
		Magnesium (Mg)	7439-95-4	0.00038	0.15000	0.06183
		Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.00746	2.95000	1.21603
		Silicon (Si)	7440-21-3	0.00162	0.64000	0.26382
	Pure metal layer	Gold (Au)	7440-57-5	0.00005	0.02000	0.00824
		Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.00415	1.64000	0.67603
		Palladium (Pd)	7440-05-3	0.00023	0.09000	0.03710
subTotal			0.25300	100.00000	41.22132	
Mould Compound	Additive	Misc. Phosphor compounds (generic)	7723-14-0	0.00031	0.10000	0.05083
		Non hazardous	Proprietary	0.01123	3.60000	1.83003
	Filler	Silica fused	60676-86-0	0.27456	88.00000	44.73410
	Pigment	Carbon black	1333-86-4	0.00062	0.20000	0.10167
		Phenolic resin	Proprietary	0.01279	4.10000	2.08420
	Polymer	Tetramethylbiphenyl diglycidyl ether	85954-11-6	0.01248	4.00000	2.03337
subTotal				0.31200	100.00000	50.83420
Wire	Gold alloy	Gold (Au)	7440-57-5	0.01417	99.00000	2.30821
		Palladium (Pd)	7440-05-3	0.00014	1.00000	0.02332
	subTotal				0.01431	100.00000

Note(s):

1) This is a generic description of the substance used as the actual composition of the substances are either considered proprietary or no official CAS number is available. If a CAS number is given, it is the closest match available.

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